Materials Declaration

Package	LFCSP
Body Size	6 X 6 X 0.85
LeadCount	40
Option	Pb-free

Molding Compound

Item	% of Compound	Weight (g)	PPM
SiO2 Filler	85	2.90 E-02	326220
Epoxy Resin	10	3.41 E-03	38379
Phenol Resin	5	1.71 E-03	19189
Subtotal		3.41 E-02	383788

Leadframe

Item	% of Leadframe	Weight (g)	PPM
Cu	97.5	4.49 E-02	504669
Fe	2.35	1.08 E-03	12164
P	0.03	1.38 E-05	155
Zn	0.12	5.52 E-05	621
Subtotal		4.60 E-02	517610

Internal Leadframe Plating

	% of Plating	Weight (g)	PPM
Ag	100	9.25 E-04	10403

External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	100	2.76 E-04	3108

Bond Wires

	% of Wire	Weight (g)	PPM
Au	99.99	9.36 E-04	10529

Chip

	% of Chip	Weight (g)	PPM
Si	100	5.68 E-03	63923

Die Attach

Item	% of Die Attach	Weight (g)	PPM
Ag Filler	75	7.09 E-04	7979
Resin	25	2.36 E-04	2660
Subtotal		9.46 E-04	10639

Package Totals

Weight (g)	PPM
8.89 E-02	1000000

Molding Compound

Item	PPM	Method
Pb	Not Detected	EPA Method 3051A/3052. ICP-OES.
Cd	Not Detected	EPA Method 3051A/3052. ICP-OES.
Hg	Not Detected	EPA Method 3051A/3052. ICP-OES.
Cr+6	Not Detected	EPA Method 3060A & &196A. UV-VIS.
PBB	Not Detected	EPA Method 3540C/3550C. GC/MS.
PBDE	Not Detected	EPA Method 3540C/3550C. GC/MS.

Die Attach Paste

Item	PPM	Method
Pb	Not Detected	EPA Method 3051A/3052. ICP-OES.
Cd	Not Detected	EPA Method 3051A/3052. ICP-OES.
Hg	Not Detected	EPA Method 3051A/3052. ICP-OES.
Cr+6	3	EPA Method 3060A & &196A. UV-VIS.
PBB	Not Detected	EPA Method 3540C/3550C. GC/MS.
PBDE	Not Detected	EPA Method 3540C/3550C. GC/MS.

Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability tc
any inaccuracy of such information.

Materials Declaration

Package	LFCSP
Body Size	6 X 6 X0.85
LeadCount	40
Option	Sn/Pb

Molding Compound

Item	% of Compound	Weight (g)	PPM
SiO2 Filler	85	2.90 E-02	326220
Epoxy Resin	10	3.41 E-03	38379
Phenol Resin	5	1.71 E-03	19189
Subtotal		3.41 E-02	383788

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P	0.03	1.38 E-05	155
Zn	0.12	5.52 E-05	621
Subtotal		4.60 E-02	517610

Internal Leadframe Plating

	% of Plating	Weight (g)	PPM
Ag	100	9.25 E-04	10403

External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	85	2.35 E-04	2642
Pb	15	4.14 E-05	466
Subtotal		2.76 E-04	3108

Bond Wires

	% of Wire	Weight (g)	PPM
Au	99.99	9.36 E-04	10529

Chip

	% of Chip	Weight (g)	PPM
Si	100	5.68 E-03	63923

Die Attach

Item	% of Die Attach	Weight (g)	PPM
Ag Filler	75	7.09 E-04	7979
Resin	25	2.36 E-04	2660
		9.46 E-04	10639

Package Totals

Weight (g)	PPM
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Molding Compound

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PBB	Not Detected	EPA Method 3540C/3550C. GC/MS.
PBDE	Not Detected	EPA Method 3540C/3550C. GC/MS.

Die Attach Paste

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Pb	Not Detected	EPA Method 3051A/3052. ICP-OES.
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